

TECHNICAL DATA SHEET

CATEGORY:

NAME:

ALLOY 40Sn/60Pb

FEATURES

HIGH PURITY

MELTING TEMPERATURE - 183°C-247°C

DESCRIPTION

40Sn/60Pb is composed of 40% Tin, and 60% Lead. This is a high purity alloy suitable for high temperature/high reliability interconnect applications with a melting point of 183°C – 247°C. 40Sn/60Pb typically is used in electronic assembly and high-temperature soldering applications. This alloy is available in solder paste, solid and cored wire, foil, preforms, powder, bar, ingot, and anode.

IMPURITY LEVELS TO IPC-JSTD-006 in Percent				
Ag: 0.05	Au: 0.05	Cu: 0.08	Ni: 0.01	
AI: 0.005	Bi: 0.10	Fe: 0.02	Sb: 0.05	
As: 0.03	Cd: 0.002	In: 0.10	Zn: 0.003	

MAJOR ALLOY INGREDIENTS in Percent				
Sn	Pb			
40% ± .50%	Remainder			

HANDLING

 This product contains lead, which is known to be a toxic element. Consult the Material Safety Data Sheet for specific handling procedures.

FLUX COMPATIBILITY

• 60/40 is compatible with most electronic grade fluxes.

CLEANING

• Refer to data sheets provided by the flux manufacturer.

SAFETY

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying Material Safety Data Sheet for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

1-1 Alloy Sn40/Pb60 09.18.00

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